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Application Data Sheet 37 CFR 1.76		Attorney Docket Number	17314-018
		Application Number	
Title of Invention	PALLADIUM-PLATED LEAD FINISHING STRUCTURE FOR SEMICONDUCTOR PART AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE		
<p>The application data sheet is part of the provisional or nonprovisional application for which it is being submitted. The following form contains the bibliographic data arranged in a format specified by the United States Patent and Trademark Office as outlined in 37 CFR 1.76.</p> <p>This document may be completed electronically and submitted to the Office in electronic format using the Electronic Filing System (EFS) or the document may be printed and included in a paper filed application.</p>			

Secrecy Order 37 CFR 5.2

<input type="checkbox"/> Portions or all of the application associated with this Application Data Sheet may fall under a Secrecy Order pursuant to 37 CFR 5.2 (Paper filers only. Applications that fall under Secrecy Order may not be filed electronically.)
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Applicant Information:

Applicant 1				
Applicant Authority		<input checked="" type="radio"/> Inventor <input type="radio"/> Legal Representative under 35 U.S.C. 117 <input type="radio"/> Party of Interest under 35 U.S.C. 118		
Prefix	Given Name		Middle Name	Family Name
	Kazumitsu			Seki
Residence Information (Select One) <input type="radio"/> US Residency <input checked="" type="radio"/> Non US Residency <input type="radio"/> Active US Military Service				
City	Nagano		Country Of Residence	JP
Citizenship under 37 CFR 1.41(b) i JP				
Mailing Address of Applicant:				
Address 1		c/o Shinko Electric Industries, Co., Ltd.		
Address 2		80, Oshimadamachi, Nagano-shi		
City	Nagano		State/Province	
Postal Code		3812287	Country	JP
Applicant 2				
Applicant Authority		<input checked="" type="radio"/> Inventor <input type="radio"/> Legal Representative under 35 U.S.C. 117 <input type="radio"/> Party of Interest under 35 U.S.C. 118		
Prefix	Given Name		Middle Name	Family Name
	Takashi			Yoshie
Residence Information (Select One) <input type="radio"/> US Residency <input checked="" type="radio"/> Non US Residency <input type="radio"/> Active US Military Service				
City	Nagano		Country Of Residence	JP
Citizenship under 37 CFR 1.41(b) i JP				
Mailing Address of Applicant:				
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Address 2		80, Oshimadamachi, Nagano-shi		
City	Nagano		State/Province	
Postal Code		3812287	Country	JP
Applicant 3				
Applicant Authority		<input checked="" type="radio"/> Inventor <input type="radio"/> Legal Representative under 35 U.S.C. 117 <input type="radio"/> Party of Interest under 35 U.S.C. 118		
Prefix	Given Name		Middle Name	Family Name
	Muneaki			Kure
Residence Information (Select One) <input type="radio"/> US Residency <input checked="" type="radio"/> Non US Residency <input type="radio"/> Active US Military Service				
City	Nagano		Country Of Residence	JP

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Citizenship under 37 CFR 1.41(b) <input type="checkbox"/>		JP	
Mailing Address of Applicant:			
Address 1		c/o Shinko Electric Industries Co., Ltd.	
Address 2		80, Oshimadamachi, Nagano-shi	
City	Nagano		State/Province
Postal Code	3812287	Country	JP
All Inventors Must Be Listed - Additional Inventor Information blocks may be generated within this form by selecting the Add button.			

Correspondence Information:

Enter either Customer Number or complete the Correspondence Information section below. For further information see 37 CFR 1.33(a).			
<input type="checkbox"/> An Address is being provided for the correspondence Information of this application.			
Customer Number	54205		
Email Address	jcalvaruso@chadbourne.com		<input type="button" value="Add Email"/> <input type="button" value="Remove Email"/>

Application Information:

Title of the Invention	PALLADIUM-PLATED LEAD FINISHING STRUCTURE FOR SEMICONDUCTOR PART AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE		
Attorney Docket Number	17314-018	Small Entity Status Claimed	<input type="checkbox"/>
Application Type	Nonprovisional		
Subject Matter	Utility		
Suggested Class (if any)		Sub Class (if any)	
Suggested Technology Center (if any)			
Total Number of Drawing Sheets (if any)	2	Suggested Figure for Publication (if any)	
Publication Information:			
<input checked="" type="checkbox"/> Request Early Publication (Fee required at time of Request 37 CFR 1.219)			
Request Not to Publish. I hereby request that the attached application not be published under 35 U.S.C. 122(b) and certify that the invention disclosed in the attached application has not been and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.			

Representative Information:

Representative information should be provided for all practitioners having a power of attorney in the application. Providing this information in the Application Data Sheet does not constitute a power of attorney in the application (see 37 CFR 1.32). Enter either Customer Number or complete the Representative Name section below. If both sections are completed the Customer Number will be used for the Representative Information during processing.			
Please Select One:		<input checked="" type="radio"/> Customer Number	<input type="radio"/> US Patent Practitioner
		<input type="radio"/> US Representative (37 CFR 11.9)	

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Customer Number	54205		

Domestic Priority Information:

This section allows for the applicant to claim benefit under 35 U.S.C. 119(e), 120, 121, or 365(c). Providing this information in the application data sheet constitutes the specific reference required by 35 U.S.C. 119(e) or 120, and 37 CFR 1.78(a)(2) or CFR 1.78(a)(4), and need not otherwise be made part of the specification.

Prior Application Status	<input type="button" value="Remove"/>		
Application Number	Continuity Type	Prior Application Number	Filing Date (YYYY-MM-DD)

Additional Domestic Priority Data may be generated within this form by selecting the **Add** button.

Foreign Priority Information:

This section allows for the applicant to claim benefit of foreign priority and to identify any prior foreign application for which priority is not claimed. Providing this information in the application data sheet constitutes the claim for priority as required by 35 U.S.C. 119(b) and 37 CFR 1.55(a).

<input type="button" value="Remove"/>			
Application Number	Country ⁱ	Parent Filing Date (YYYY-MM-DD)	Priority Claimed
2004-154656	JP	2004-05-25	<input checked="" type="radio"/> Yes <input type="radio"/> No
Additional Foreign Priority Data may be generated within this form by selecting the Add button.			

Assignee Information:

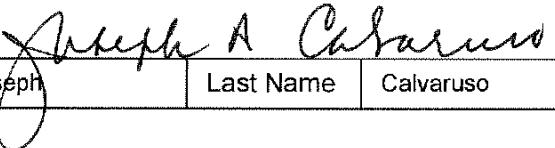
Providing this information in the application data sheet does not substitute for compliance with any requirement of part 3 of Title 37 of the CFR to have an assignment recorded in the Office.

Assignee 1			
If the Assignee is an Organization check here. <input checked="" type="checkbox"/>			
Organization Name	Shinko Electric Industries Co., Ltd.		
Mailing Address Information:			
Address 1	80 Oshimadamachi, Nagano-shi		
Address 2			
City	Nagano	State/Province	
Country ⁱ	JP	Postal Code	3812287
Phone Number		Fax Number	
Email Address			
Additional Assignee Data may be generated within this form by selecting the Add button.			

Signature:

A signature of the applicant or representative is required in accordance with 37 CFR 1.33 and 10.18. Please see 37 CFR 1.4(d) for the form of the signature.

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Signature			Date (YYYY-MM-DD)	2006-10-04	
First Name	Joseph	Last Name	Calvaruso	Registration Number	28287

This collection of information is required by 37 CFR 1.76. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 23 minutes to complete, including gathering, preparing, and submitting the completed application data sheet form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.